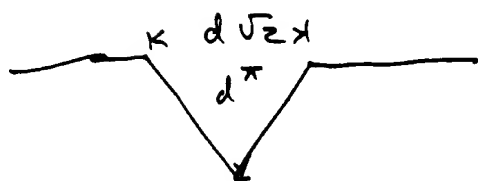
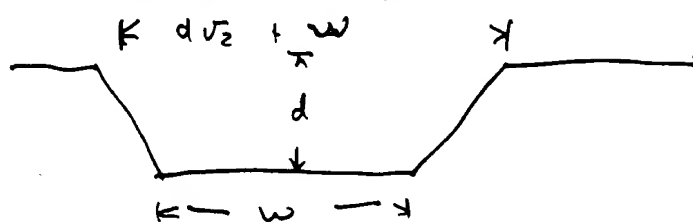


NORTHROP EXHIBIT N



Scribe line \approx 70% thickness



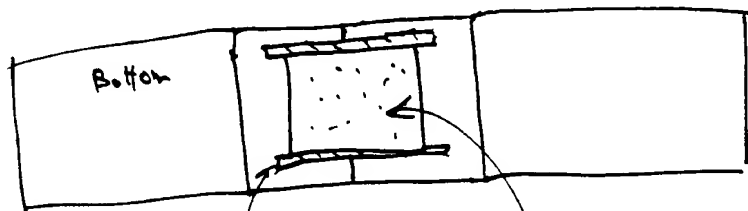
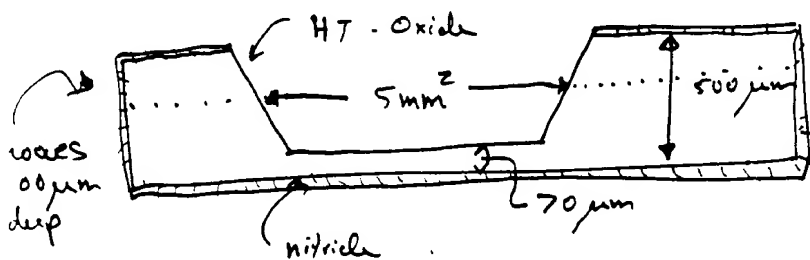
or

Syringe - U. groove



M. All *[Signature]*

B) Summary of recent design meeting
w/ Courtney and Jim on



Bond pads

polyheater/poly silicon

Processing Steps:

- 1) RCA Clean
- 2) Tunnel oxide
- 3) Polysilicon dep.
- 4) Dope poly (phos) dep. have
- 5) dep. Si₃N₄
- 6) Pattern well-side
 - 1) wells
 - 2) V-grooves
 - 3) Scribe lines
- 7) Plasma etch
- 8) KOH - timed etch
- 9) Strip Si₃N₄
- 10) Strip oxide